Editorial Comment

This document defines the syntax and semantics for EDIF Version 4 0 0, IEC 61690-2. EDIF Version 4 0 0 addresses EDIF Level 0 and Level 1. EDIF Version 3 0 0 provides support for Connectivity and Schematics; EDIF Version 4 0 0 offers additional capability by providing support for the representation of Printed Circuit Boards (PCBs) and Multi-chip Modules (MCMs) including technology rules and assembly drawings.

Since the release of EDIF Version 3 0 0 (ANSI/EIA-618-1993), considerable effort has been expended within the EDIF PCB/MCM Technical Subcommittee and the EDIF Technical Experts Group to widen the scope of EDIF.

The objectives of this version of EDIF are summarized as follows:

- support the transfer of complex schematic drawings

- support the transfer of structured connectivity information

- support the transfer of printed circuit board, printed circuit assembly and multi-chip module information

The information modelling language EXPRESS (ISO 10303 Part 11) has been used to develop the underlying information model of EDIF. The EDIF Version 4 0 0 syntax is based on, and is intended to be consistent with, this underlying information model. In the event of discrepancy between the information model and the reference manual, the information model takes precedence.

The views addressed in this release are PCB/MCM, Schematic and Connectivity views. Less utilized views (Behavior view, LogicModel view, MaskLayout view, and the SymbolicLayout view) are represented by stubs in this release.

In the areas of Schematic and Connectivity views, EDIF Version 4 0 0 is compatible with EDIF Version 3 0 0 (IEC 61690-1:2000, ANSI/EIA-618-1993).

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